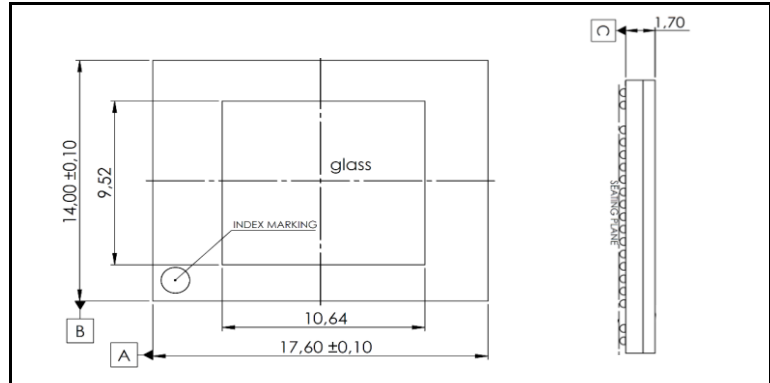
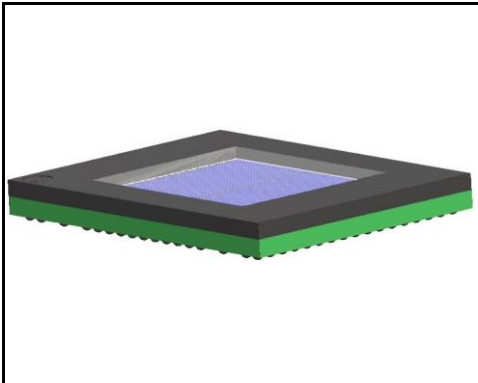


Preliminary for Engineering Samples



### Features

- 64 element APD array
- High QE >80% for  $\lambda = 760-910$  nm
- High speed, low noise

### Description

Matrix APD array for NIR detection. PCB based BGA package with on active area of APD glued AR coated glass. Non hermetic, suitable for reflow soldering.

### Application

Automotive and industrial LiDAR (AECQ-102 pending)

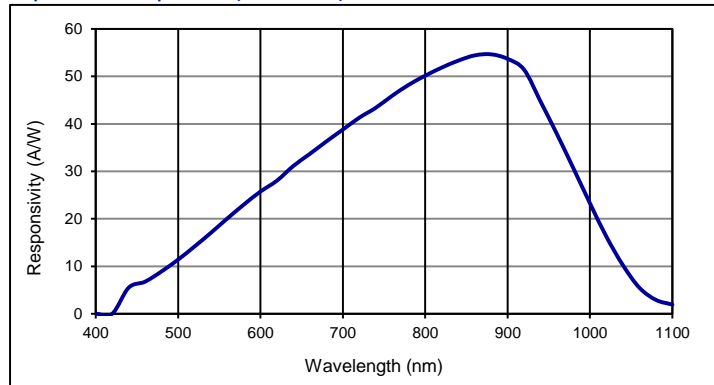
### RoHS

2011/65/EU

### Absolute maximum ratings

Symbol	Parameter	Min	Max	Unit
$T_{STG}$	Storage temp	-40	125	°C
$T_{OP}$	Operating temp	-40	125	°C
$M_{max}$	Gain ( $I_{PD} = 1$ nA)	200		
$I_{PEAK}$	Peak DC current (linearity)		0.25	mA

### Spectral response (M = 100)



### Electro-optical characteristics @ 23°C

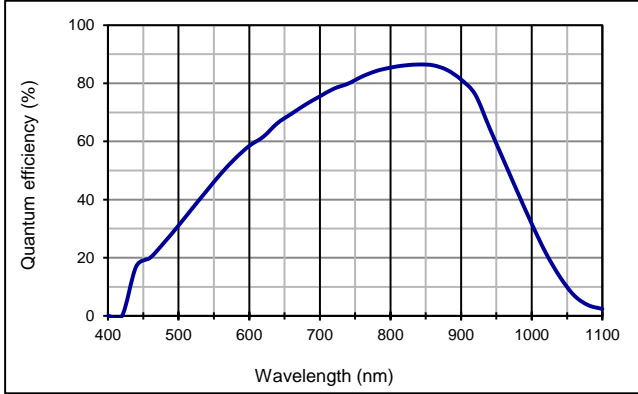
Symbol	Characteristic	Test Condition	Min	Typ	Max	125°C*	Unit
	No of elements			64			
	Active area			240 x 5000			μm
	Gap; Pitch			40 ; 280			μm
$I_D$	Dark current	M = 50, per element		0.25	1.5	1500	nA
C	Capacitance	M = 50, per element			3		pF
	Responsivity	M = 100; $\lambda = 905$ nm	49.5	55			A/W
$t_R$	Rise time	M = 100; $\lambda = 905$ nm; $R_L = 50 \Omega$			1.5		ns
$V_{BR}$	Breakdown voltage	$I_R = 10 \mu A$	180		240	400	V
$T_K$	Temperature coefficient	$U_{br}$		1.49			V/K
	Cross talk suppression	DC, M=50, $\lambda = 905$ nm	40	46			dB
	Gain uniformity	M = 50		$\pm 10$	$\pm 30$		%
Rabs	ARC on cover glass***	880 nm to 940 nm; AOI $_{max}$ =45°		1	2		%

\* maximal value

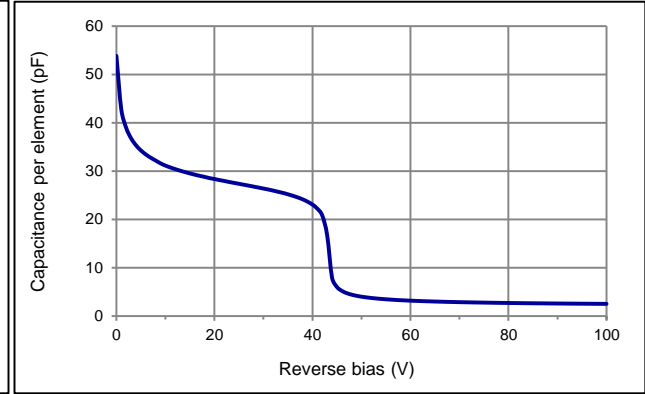
\*\* middle of pixel, spot size = 10 μm diameter

\*\*\* single sided, non transparent at visible wavelength (black ARC)

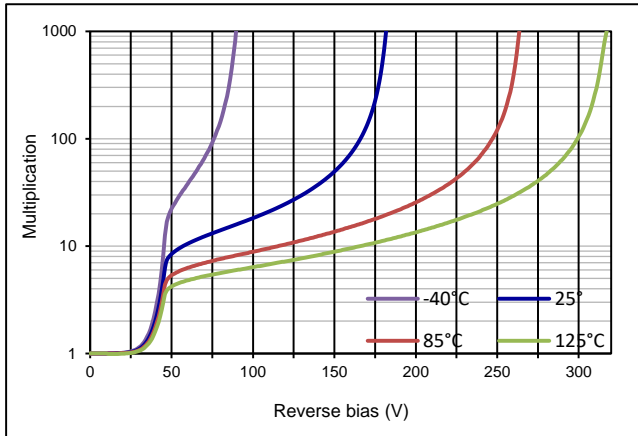
Quantum efficiency (23 °C)



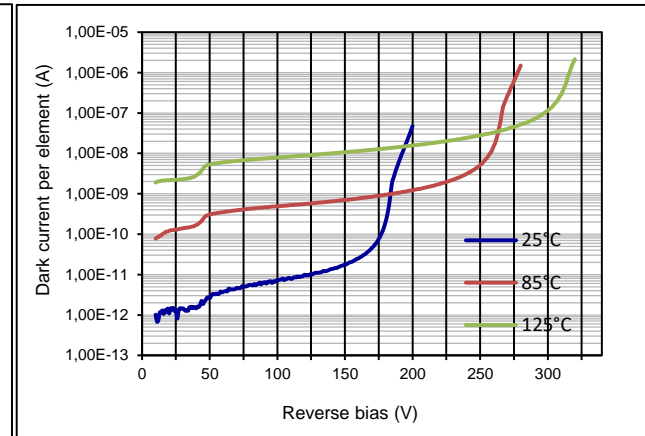
Capacitance as fct of reverse bias (23 °C)



Multiplication as fct of reverse bias\*\*\*\*

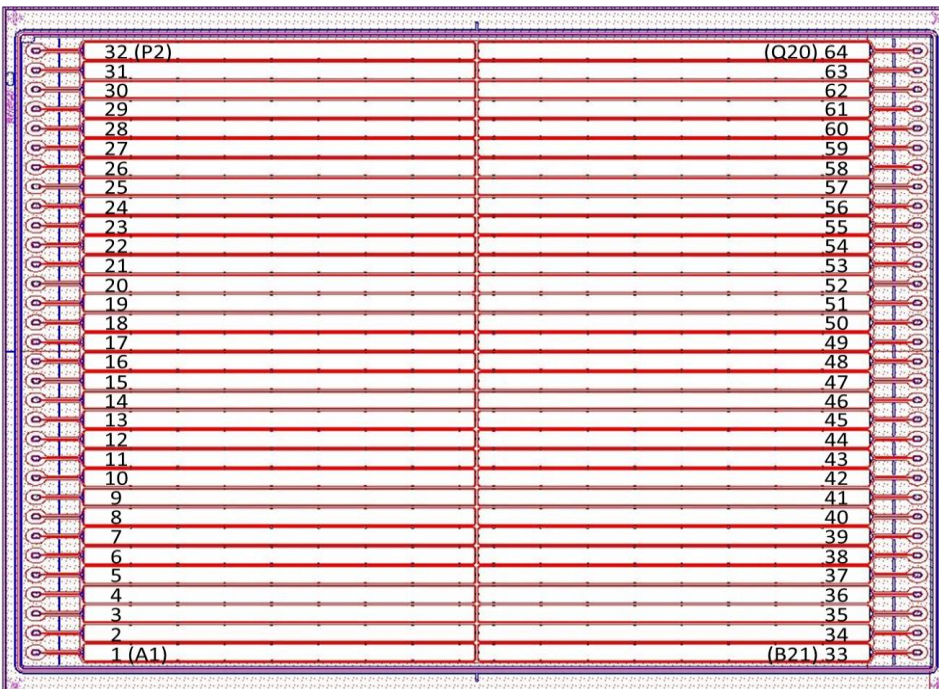


Dark current as fct of reverse bias

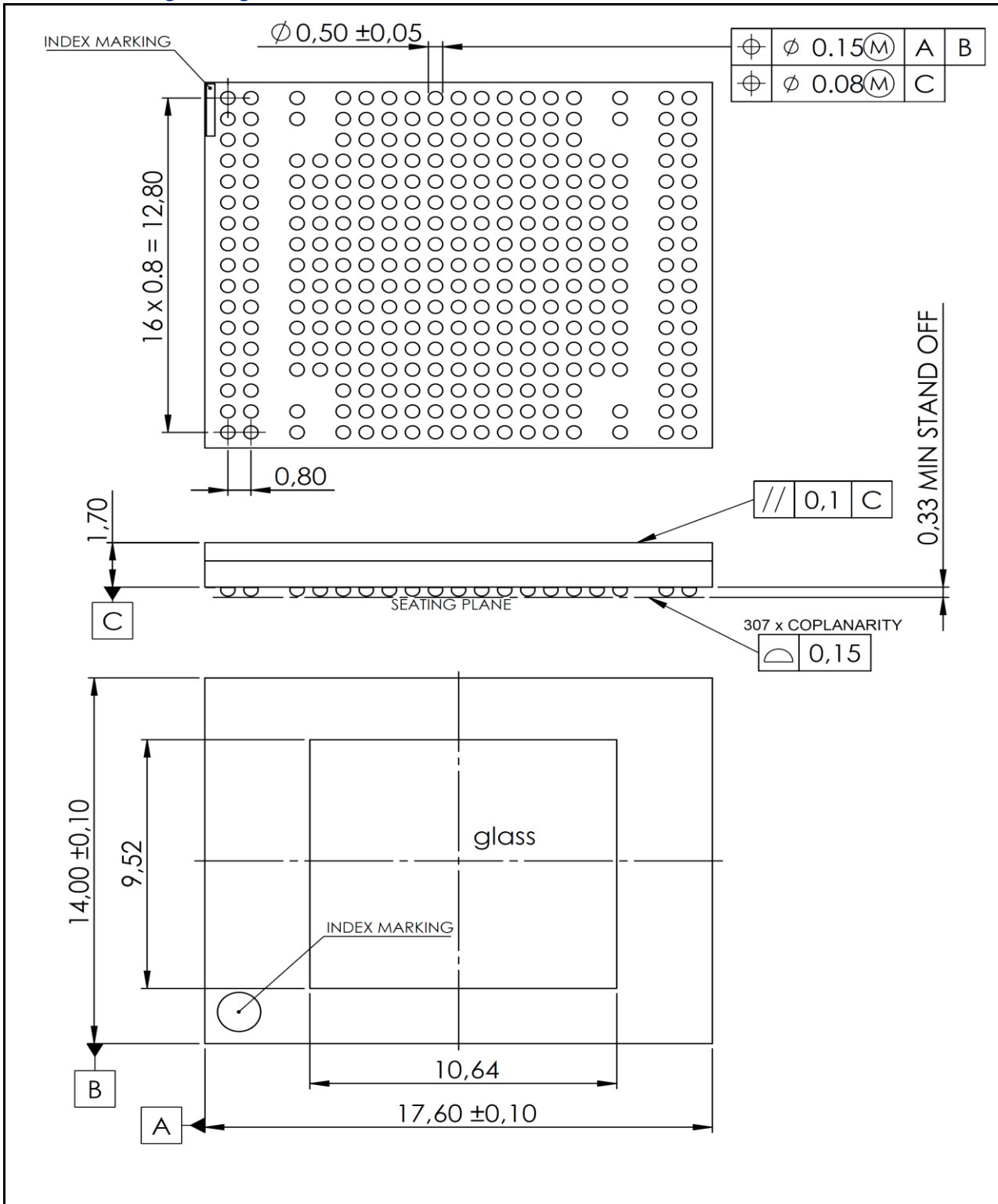


\*\*\*\* Illumination with 10 nW optical power

Chip drawing 64AA1.2-9



Technical Drawing, Package BGA



Pinning (top view)

	1	2	3	4	5	6-9	10	11	12	13-16	17	18	19	20	21
Q	G	Gnd		A		n.c.	n.c.	n.c.	n.c.	n.c.		A		C64	C63
P	C31	C32		A		n.c.	n.c.	n.c.	n.c.	n.c.		A		C62	C61
O	C29	C30				n.c.	n.c.	n.c.	n.c.	n.c.				C60	C59
N	C27	C28		n.c.	n.c.	n.c.	n.c.	n.c.	n.c.	n.c.	n.c.	n.c.		C58	C57
M	C25	C26		n.c.	n.c.	n.c.	n.c.	n.c.	n.c.	n.c.	n.c.	n.c.		C56	C55
L	C23	C24		n.c.	n.c.	n.c.	n.c.	n.c.	n.c.	n.c.	n.c.	n.c.		C54	C53
K	C21	C22		n.c.	n.c.	n.c.	n.c.	n.c.	n.c.	n.c.	n.c.	n.c.		C52	C51
J	C19	C20		n.c.	n.c.	n.c.	n.c.	n.c.	n.c.	n.c.	n.c.	n.c.		C50	C49
I	C17	C18		n.c.	n.c.	n.c.	n.c.	n.c.	n.c.	n.c.	n.c.	n.c.		C48	C47
H	C15	C16		n.c.	n.c.	n.c.	n.c.	n.c.	n.c.	n.c.	n.c.	n.c.		C46	C45
G	C13	C14		n.c.	n.c.	n.c.	n.c.	n.c.	n.c.	n.c.	n.c.	n.c.		C44	C43
F	C11	C12		n.c.	n.c.	n.c.	n.c.	n.c.	n.c.	n.c.	n.c.	n.c.		C42	C41
E	C9	C10		n.c.	n.c.	n.c.	n.c.	n.c.	n.c.	n.c.	n.c.	n.c.		C40	C39
D	C7	C8		n.c.	n.c.	n.c.	n.c.	n.c.	n.c.	n.c.	n.c.	n.c.		C38	C37
C	C5	C6				n.c.	n.c.	n.c.	n.c.	n.c.				C36	C35
B	C3	C4		A		n.c.	n.c.	n.c.	n.c.	n.c.		A		C34	C33
A	C1	C2		A		n.c.	n.c.	n.c.	n.c.	n.c.		A		Gnd	G

- A Anode
- C Cathode
- n.c. not connected
- Gnd Ground
- G Guard (It is recommended to connect only one guard contact and to connect it by 33 kOhm against ground potential, see "application-note-apd-array.pdf")

Package dimension

For small quantities chip trays are available.

Handling:

Please refer to document "Instructions for handling and processing"

Application hints:

Please refer to document: "application-note-apd-array"